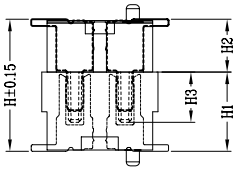
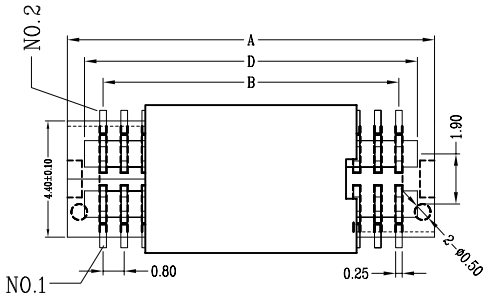
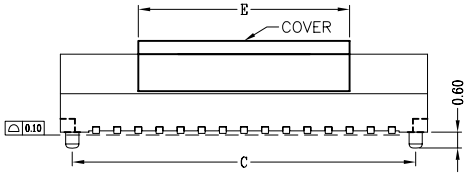
REV	ECN	DESCRIPTION	MDF'D	DATE
1.0	/	新发行	fan Z.J.	2021-07-08

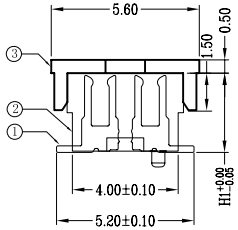
High photosynthesis (H)	The female seat height (H1)	The male seat height (H2)	Insertion height (H3)
4.0	3.0	1.0	1.9
4.5	3.5	1.0	1.9
5.0	3.0/4.0	2.0/1.0	1.9
5.5	3.5/4.5	2.0/1.0	1.9
6.0	4.0	2.0	1.9
6.5	4.5	2.0	1.9
7.0	3.0	4.0	1.9
7.5	3.5	4.0	1.9
8.0	4.0	4.0	1.9
8.5	4.5	4.0	1.9

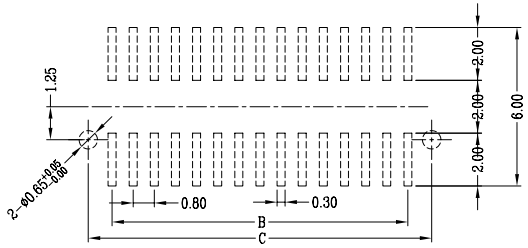


ASSEMBLY









P.B.C LAYOUT

5001-BTB 0845-** F R-00-B

- PACKING:R:REEL
- FEMALE
- PIN
- HEIGHT: 30-3.0H;35-3.5H 40-4.0H;45-4.5H.
- 0.8BTB
- JM CONN BTB CONNECTOR SERIES

NO. of Contacts	Dimension(mm) A±0.10	B±0.10	C±0.10	D±0.10	E±0.10
6	4.30	1.60	3.40	2.66	
8	5.10	2.40	4.20	3.46	
10	5.90	3.20	5.00	4.26	
12	6.70	4.00	5.80	5.06	
14	7.50	4.80	6.60	5.86	
16	8.30	5.60	7.40	6.66	
18	9.10	6.40	8.20	7.46	
20	9.90	7.20	9.00	8.26	
22	10.70	8.00	9.80	9.06	4.00
24	11.50	8.80	10.60	9.86	
26	12.30	9.60	11.40	10.66	
28	13.10	10.40	12.20	11.46	
30	13.90	11.20	13.00	12.26	
32	14.70	12.00	13.80	13.06	
34	15.50	12.80	14.60	13.86	
36	16.30	13.60	15.40	14.66	
38	17.10	14.40	16.20	15.46	
40	17.90	15.20	17.00	16.26	
42	18.70	16.00	17.80	17.06	
44	19.50	16.80	18.60	17.86	
46	20.30	17.60	19.40	18.66	
48	21.10	18.40	20.20	19.46	
50	21.90	19.20	21.00	20.26	
52	22.70	20.00	21.80	20.86	
54	23.50	20.80	22.60	21.86	
56	24.30	21.60	23.40	22.66	
58	25.10	22.40	24.20	23.46	
60	25.90	23.20	25.00	24.26	
62	26.70	24.00	25.80	25.06	
64	27.50	24.80	26.60	25.86	
66	28.30	25.60	27.40	26.66	
68	29.10	26.40	28.20	27.46	8.00
70	29.90	27.20	29.00	28.26	
72	30.70	28.00	29.80	29.06	
74	31.50	28.80	30.60	29.86	
76	32.30	29.60	31.40	30.66	
78	33.10	30.40	32.20	31.46	
80	33.90	31.20	33.00	32.26	
82	34.70	32.00	33.80	33.06	
84	35.50	32.80	34.60	33.86	
86	36.30	33.60	35.40	34.66	
88	37.10	34.40	36.20	35.46	
90	37.90	35.20	37.00	36.26	
92	38.70	36.00	37.80	37.06	
94	39.50	36.80	38.60	37.86	
96	40.30	37.60	39.40	38.66	
98	41.10	38.40	40.20	39.46	
100	41.90	39.20	41.00	40.26	

No.	品名	数量	材料	表面处理	备注
1	端子	PIN数	C5191 H	全金Flash 0.6U"	
2	本体	1	PANT 黑色	———	
3	CAP	1	PANT 黑色	———	

.X ±0.20	.X° ±1.0°		
.XX ±0.10	.XX° ±0.5°		
.XXX ±0.05	.XXX° ±0.2°		
	SCALE 1:1	UNIT mm	
PAGE: 1/1	REV: 1.0		

东莞市文章济美电子有限公司

Part Name: B T B 0.8双排 母座		Approved:
Part No.: 5001-BTB0845-24FR-00-B		Checked:
Title:	Material:----	Drawn: Fan Z.J.
Drawing No.:G8BTC0003	Mode NO.:	Date: 2021-07-08

1. SCOPE

1.1. CONTENTS

This specification covers the performance, tests and quality requirements for the 0.8mm Pitch BOARD to BOARD SMD V/T Type Connector . (MATING HEIGHT: 4.0H-8.5H)

2. APPLICABLE DOCUMENT

The following JMCONN documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawings, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

3. REQUIREMENTS

3.1. DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawings.

3.2. MATERIALS

A. Housing: PA9T HIGH-TEMP THERMOPLASTIC, UL94V-0, BLACK.

B. Terminal: Phosphor， 1μ " Gold-Flash under-plated Ni overall.

3.3. RATINGS

A. Voltage rating:60V DC

B. Current rating: 0.5A Max.((Each Pin)

C. Operating Temperature: - 25℃ to +85℃ (Including terminal temperature rise)

D. Operating Humidity range: Relative humidity 93%Max

E. Storage temperature range:20±8℃

F. Storage Humidity range: Relative humidity 60%Max

3.4. PERFORMANCE REQUEIREMENT AND TEST DESCRIPTION

The product shall be designed to meet the electrical, mechanical and environmental performance Requirements specified in Figure 1. All tests shall be performed at ambient environmental conditions.

	测试项目 TEST ITEM	规格 REQUIREMENT	测试方式/条件 PROCEDURE
1	外观检查 Examination of Product	符合图面外观，无任何形状损坏 Meets requirements of product Drawing. No physical damage.	目视检查 Visual inspection.
	电气特性 ELECTRICAL REQUIREMENT		
2	接触电阻 Contact Resistance	60mΩ 以下。 60mΩ Max.	将样品成对连接，开放电压 20mV 以下；限电流 100mA 的状态下进行测试。 Mate The sample connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
3	绝缘阻抗 Insulation Resistance	800MΩ 以上。 800MΩ Min.	未连接的样品，提供相邻端子间或端子与地面间加 DC 500V 进行绝缘阻抗测试。 Unmated The sample connectors，apply 500V DC between adjacent terminal or ground. (EIA-364-21)
4	耐电压 Dielectric withstanding Voltage	目视外观无任何击穿损坏 No Breakdown 电流泄漏： 1 mA max. Current leakage: 1 mA max.	未连接的样品，提供相邻端子间或端子与地面间加 AC 500V（有效值）历时 1 分钟下测定耐电压。 Unmated The sample connectors，Apply 500 V AC for 1minute Test between adjacent circuit of unmated connector. (EIA-364-20)
	机械特性 MECHANICAL REQUIREMENT		
5	接触保持力 Contact Retention Force	0.03Kgf/Pin{0.294N}以上 0.03Kgf//Pin {0.294N}Min.	将样品成对连接，以操作速度每分钟位移 25±3mm 进行接触保持力测试。 Load shall be applied on each at a speed of 25±3mm/minute as shown below then pin retention force shall be measured.
6	插入力 Insertion Force	0.12KgfxN Max. (N=Pins) 0.12KgfxN Max. (N=Pins)	将成对连接器焊板连接，以操作速度每分钟位移 25±3mm 进行插入力测试。 Mate The sample connectors shall be soldered on a board and inserted and separated at speed of 25±3mm/min. (EIA-364-13)

测试项目 TEST ITEM		规格 REQUIREMENT		测试方式/条件 PROCEDURE
机械特性 MECHANICAL REQUIREMENT				
7	耐插拔 Durability	外观 Appearance	目视外观无任何损坏异状 No Damage	将样品成对连接，以操作速度每分钟位移 25±3mm 进行 30 次插拔测试。 Mate The sample connectors should be mounted in the tester and fully mated and unmated the number of 30cycles specified at the rate of 25±3 mm/min. (EIA-364-09)
		接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	
8	耐振动 Vibration	接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	通过 DC 电流 1mA,位移相对距离 1.5mm，振动周期 10~55~10Hz 在 1 分钟内，持续 2 小时，方向在 X，Y，Z 轴做测试 Mate connectors and subject to the following vibration conditions for period of 2 hours in each of 3 mutually perpendicular axes passing DC 1mA during the test.Amplitude:1.5mm P-P frequency:10~55~10 Hz in 1 minute (EIA-364-28 Condition I)
		外观 Appearance	目视外观无任何损坏异状 No Damage	
		瞬间断电 Discontinuity	1 μ sec 以下. 1 μ sec Max.	
9	耐冲击性 Shock (Mechanical)	外观 Appearance	目视外观无任何损坏异状 No Damage	将样品成对连接，通过 DC1mA 测试条件，连续测试 3 次。在 X、Y、Z 3 轴 6 个垂直方向施予重力加速度 490m/s^2{50G}冲击。 Mate The sample connectors shall and subject to the following shock condition.3 times of shocks shall be applied for each 6 directions along 3 mutually perpendicular axes, passing DC 1mA current during the test.(Total of 18 shocks) Peak value490m/s^2{50G} (EIA-364-27, test condition A)
		接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	
		瞬间断电 Discontinuity	1 μ sec 以下. 1 μ sec Max..	
环境特性及其它性能（ENVIRONMENT PERFORMANCE AND OTHERS）				
10	温升 Temperature Rising	负载额定电流下温度 30℃ 30℃ Max. Under loaded rating current		量测通过成对连样品接最大容许电流时，样品接触点这温升。 Mate The sample connectors and measure the temperature rise of contact when the maximum AC rated current is passed. (EIA-364-70 METHOD 2)

测试项目 TEST ITEM		规格 REQUIREMENT		测试方式/条件 PROCEDURE
环境特性及其它性能（ENVIRONMENT PERFORMANCE AND OTHERS）				
11	耐热性 Heat Resistance	外观 Appearance	目视外观无任何损坏异状 No Damage	将样品成对连接置于环境温度 85±2℃测试时间 96 小时。再置放于室温下 1~2 小时。 Mate The sample connectors shall expose to 85±2℃ for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room condition for 1to2 hours, after which the specified measurements shall be performed.
		接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	
12	耐寒性 Cold Resistance	外观 Appearance	目视外观无任何损坏异状 No Damage	将样品成对连接置于环境温度-25±2℃测试时间 96 小时。再置放于室温下 1~2 小时。 Mate The sample connectors shall expose to -25±2℃ for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room condition for 1to2 hours, after which the specified measurements shall be performed.
		接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	
11	耐湿性 Humidity	接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	将样品成对连接置于环境温度 40±2℃，相对湿度 90~95%，测试时间 96 小时。再置放于室温下 1~2 小时。 Mate The sample connectors shall expose to 40±2℃ relative humidity 90~95% for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room condition for 1to2 hours, after which the specified measurements shall be performed.
		耐电压 Dielectric Strength	需能符合电压试 No Breakdown	
		外观 Appearance	目视外观无任何损坏异状 No Damage	
		绝缘阻抗 Insulation Resistance	500MΩ 以上。 500MΩ Min.	

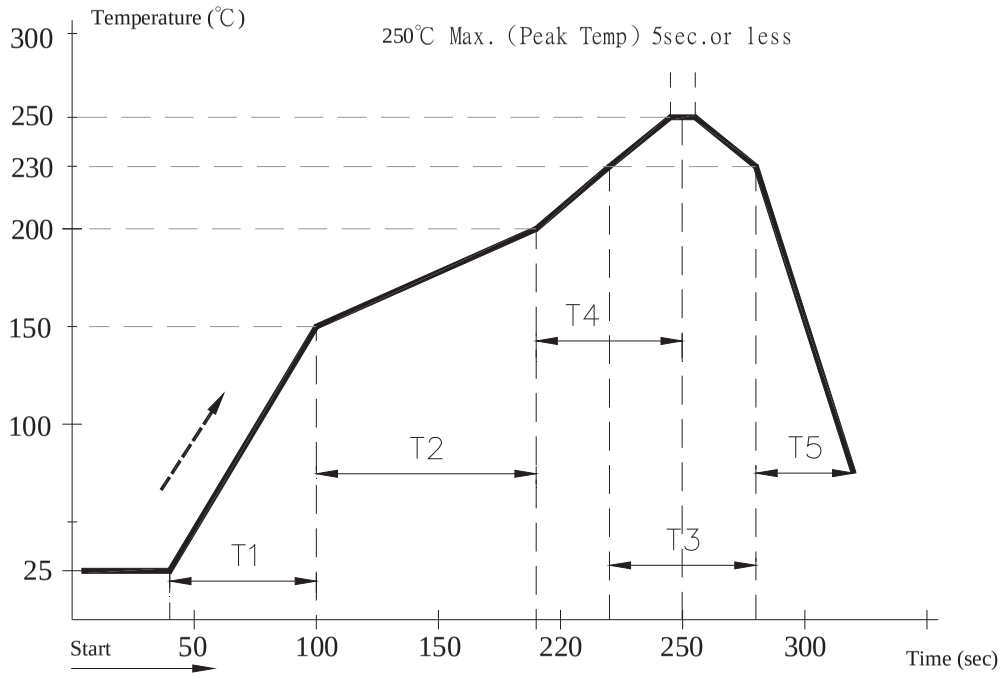
测试项目 TEST ITEM		规格 REQUIREMENT		测试方式/条件 PROCEDURE
环境特性及其它性能（ENVIRONMENT PERFORMANCE AND OTHERS）				
12	冷热冲击 Temperature Cycling	接触阻抗 Contact Resistance	90mΩ 以下. 90mΩ Max.	将样品成对连接，承受 5 cycles 冷热冲击后，置放于室温下 1~2 小时。1cycle time 如下 a)-25±3℃,30 分钟 b) +85±3℃,30 分钟 A connector shall and subject to the following condition for 5 cycles .Upon completion of the exposure period, the test specimens shall be conditioned at ambient room condition for 1to2 hours, after which the specified measurements shall be performed. 1cycle a)-25±3℃,30 minutes b) +85±3℃,30 minutes (Transit time shall be with in 3 minutes) (EIA-364-31, Test condition A)
		外观 Appearance	目视外观无任何损坏异状 No Damage	
13	盐水喷雾 Salt Spray	外观 Appearance	目视外观无任何损坏异状 No Damage	将样品成对连接，使用 5±1%浓度盐水，测试温度 35±2℃，测试时间 24 小时后，于室温下使用清水冲洗后再干燥。 Mate The sample connectors shall expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified NaCl solution Concentration:5±1% Spray time:24hours Ambient temperature:35±2℃ (EIA-364-26,Test condition B)
14	焊锡性 Solder ability	润湿性 Solder Wetting	润湿面积 95%以上,并不得有漏焊针孔现象。 95% of immersed area must show no voids, pin holes.	锡温 250±5℃，将导电端子浸入锡炉液面至 Housing 距离锡面 0.1mm 位置，焊锡时间 3±0.5 秒。 Tip of solder tails and fitting mails into the molten solder (held at 250±5℃) up to 0.1mm from the Housing for 3±0.5sec onds. (EIA-364-52)

测试项目 TEST ITEM		规格 REQUIREMENT		测试方式/条件 PROCEDURE
环境特性及其它性能（ENVIRONMENT PERFORMANCE AND OTHERS）				
15	焊锡耐热性 Resistance to Reflow Soldering Heat	外观 Appearance	目视外观无任何损坏异状 No Damage	使用红外线回流焊时请参考第 4 点 When reflowing….Refer to paragraph 4. 使用烙铁手焊时须符合下述焊锡条件 Soldering iron method 0.2 mm from terminal tip and fitting nail tip. Soldering time:5 seconds Max. Soldering temperature:370~400℃

Figure 1

NOTE: Shall meet visual requirements, show no physical damage, and meet requirement of additional tests as specified in the test sequence in Figures 2

4. INFRARED REFLOW CONDITION (Lead Free)



T1	Temperature Ramp Up Rate	2℃~5℃/Sec
T2	Preheat:150℃~200℃	60~90Sec
T3	Time Over 230℃	30~50Sec
T4	Preheat:200℃~250℃	30Sec
T5	Ramp Down Rate During Cooling	4℃~7℃/Sec
	Peak Temperature	250℃Max

NOTE:

Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C.Boarde and so on.

5.0. PRODUCT QUALIFICATION AND RELIABILITY TEST SEQUENCE

Test or Examination	Test Group											
	A	B	C	D	E	F	G	H	I	J	K	L
Appearance (外观)	1;7	1;3	1;6	1;6	1;6	1;3	1;6	1;6	1;5	1;5	1;3	1;3
Contact Resistance (接触电阻)			2;5	2;5	2;5		2;5	2;5	2;4	2;4		
Dielectric Withstanding Voltage (耐电压)	3;6											
Insulation Resistance (绝缘阻抗)	2;5											
Insertion Force (插入力)		2										
Contact Retention Force（接触保持力）			3,4									
Vibration(耐振动)				3,4								
Shock Mechanical (耐冲击性)					3,4							
Temperature Rising (温升)						2						
Heat Resistance(抗热性)							3,4					
Cold Resistance(耐寒性)								3,4				
Humidity(耐湿性)	4											
Temperature Cycling (温度循环)									3			
Salt Spray(盐水喷雾)										3		
Solder ability (可焊性)											2	
Resistance to Soldering Heat (焊锡耐热性)												2

Figure 2

NOTE: (a) Numbers indicate sequence in which tests are performed.
(b) Discontinuities shall not take place in this test group, during test